

»Performance Specification

Model	I-hold	I-trip	Vmax	Imax	Pd typ	Max. Time to trip		R0 min	R1max
						Current	Time		
	(A)	(A)	(Vdc)	(A)	(W)	(A)	(Sec.)	(Ohm)	(Ohm)
SMD0805-075/16N	0.75	1.50	6.00	100.00	0.60	8.00	0.20	0.09	0.35

I-hold: Holding Current: maximum current at which the device will not trip in 25°C still air.

I-trip: Tripping Current: minimum current at which the device will trip in 25°C still air.

Vmax: Maximum voltage device can withstand without damage at rated current(Imax).

I max: Maximum fault current device can withstand without damage at rated voltage(Vmax).

Pd typ: Typical power dissipated from device when in the tripped state at 25°C still air.

R0 min: Minimum resistance of device in initial (un-soldered) state.

R1 max: Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

»Thermal Derating Chart Recommended Hold Current(A) at Ambient Temperature(°C)

Model	Ambient Operating Temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD0805-075/16N	1.00	0.90	0.80	0.75	0.63	0.57	0.53	0.41	0.34

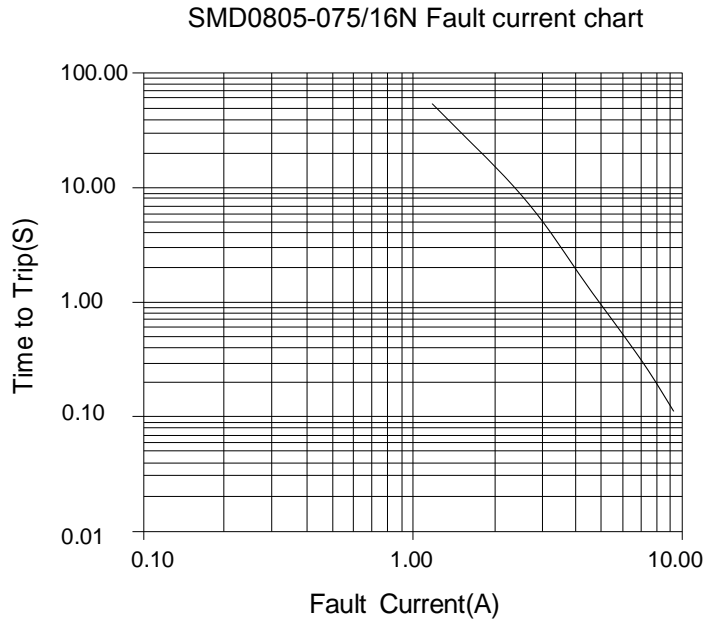
»Environmental Specifications

Operating Temperature	-40 °C to +85 °C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85 °C, 1000 hours ; ±5 % typical resistance change
Humidity Aging	+85 °C, 85 % R.H. 1000 hours; ±5 % typical resistance change
Thermal Shock	MIL-STD-202, Method 107; +85 °C to -40 °C, 20 times;-30 % typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 ; No change
Vibration	MIL-STD-883, Method 2007, Condition A; No change
Moisture Sensivity Level	Level 1, J-STD-020
Storage Conditions	+40 °C Max. 70% RH Max. Packed in original packaging.

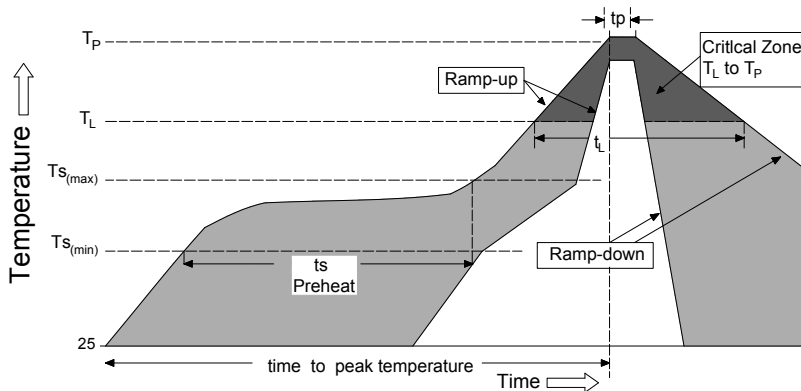
»Test Procedures And Requirements

No.	Test	Test Conditions	Accept/Reject Criteria
1	R0 min	Resistance measurement at 25°C	$R0min \leq R \leq R1max$
2	R1 max	Resistance measurement one hour after post trip	$R0min \leq R \leq R1max$
3	I-hold	Hold rated current 1800 second without trip, @ 25°C	No trip
4	I-trip	Device must trip within 900 second under rated current, @25°C	Trip
5	Max. time to trip	At specified current, 25 °C	$T \leq \text{max. time to trip (seconds)}$
6	Trip Cycle Life	Vmax, Imax, 100 cycles	No arcing or burning
7	Trip Endurance	Vmax,Imax 24 hours	No arcing or burning
8	Solderability	ANSI/J-STD-002	95 % min. coverage

»Typical time to trip at 25°C



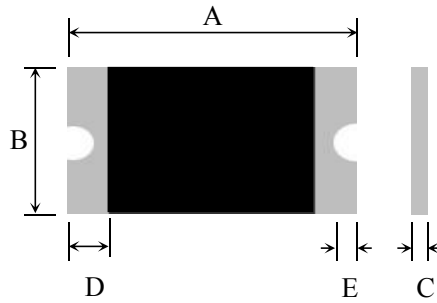
»Soldering Parameters



Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate (Ts(max) to TP)		3°C/second max
Pre Heat:	Temperature Min (Ts(min))	150°C
	Temperature Max (Ts(max))	200°C
	Time (Min to Max) (ts)	60 – 180 secs
Time Maintained Above:	Temperature (Tl)	217°C
	Temperature (tl)	60 – 150 seconds
Peak / Classification Temperature (TP)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (tp)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (TP)		8 minutes Max.

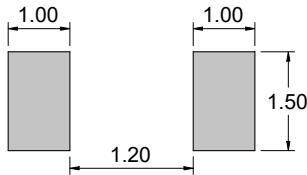
- ◆All temperature refer to topside of the package, measured on the package body surface
- ◆If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- ◆Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead
- ◆Recommended maximum paste thickness is 0.25mm (0.010inch)
- ◆Devices can be cleaned using standard industry methods and solvents

»Physical Dimensions(mm)



Model	A		B		C		D		E
	Min	Max	Min	Max	Min	Max	Min	Max	Min
SMD0805-075/16N	2.00	2.30	1.20	1.50	0.65	1.15	0.20	0.55	0.10

»Recommended Pad Layout (mm)&Physical Specifications



Terminal Material	Tin-Plated Nickle-Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

»Tape And Reel Specifications (mm)&Packaging quantity

TAPE SPECIFICATIONS: EIA-481-1 (mm)	
W	8.10±0.10
F	3.50±0.05
E1	1.75±0.10
D0	1.55±0.05
D1	1.00 min
P0	4.0±0.10
P1	4.0±0.10
P2	2.0±0.05
A0	1.70±0.10
B0	2.45±0.10
T	0.25±0.05
K0	0.95±0.10
Leader	390mm
Trailer	160mm
Q'ty	4,000pcs/Reel

REEL DIMENSIONS: EIA-481-1 (mm)	
C	Ø178±1.0
D	Ø60.2±0.5
W	9.0±1.5
H	11.0±0.5

